

Thermal Grease TG1500I

BENEFITS AND FEATURES

- Low viscosity, easy to print with screen printing process
- Solvent free
- Low BLT & low thermal resistance
- High insulation

OVERVIEW

Honeywell TG1500I is a silicone based thermal grease with low viscosity. Its excellent wetting capability and thin bond line thickness helps to achieve the minimal thermal resistance. Meanwhile, it can mate the interfaces well even under low mounting stress, and be applied on the Sumstrate smoothly by screen printing, stencil printing or diepensing. TG1500I is stable and it does not dry out, low risk on oil separation or Harden. Above properties make it widely used as TIM solution for chips.

TYPICAL APPLICATIONS

- GPU, CPU and other chipset
- North bridge chipset
- Chassis and associated cooling module
- LED lightings

STORAGE & USE

Shelf Life: 12 months from manufacturing

Storage: 0-35°C, <65%RH

Package: 30cc syringe

300cc Aluminum tube

1 kg Jar

5 Gallon Pail

Property	TG1500I	Test Method
Color	White	Visual
Thermal conductivity (W/m· K)	1.5	ASTM D5470
Thermal impedance (cm ² .K/W)	0.18	ASTM D5470
Viscosity (Pa.s)	250	ASTM D2196
Specific gravity	2.7	ASTM D792
TLM(%)	0.02	ASTM E595
Volume resistivity (Ohm.cm)	> 10 ¹³	ASTM D257
Dielectric constant@1MHz	> 5	ASTM D150
Dielectric strength (KV/mm)	> 8	ASTM D149
Flame retardancy	V-0 equivalent	UL 94
Working temperature (°C)	-40~200	HON internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

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